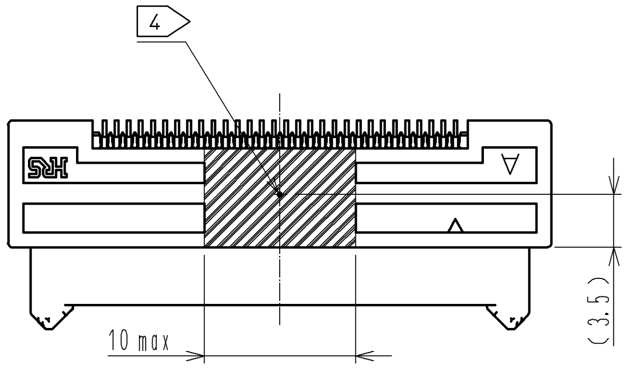
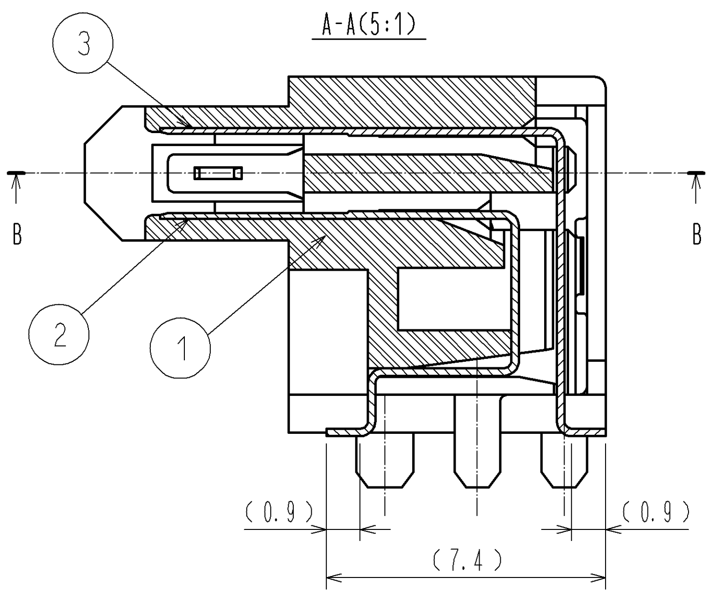
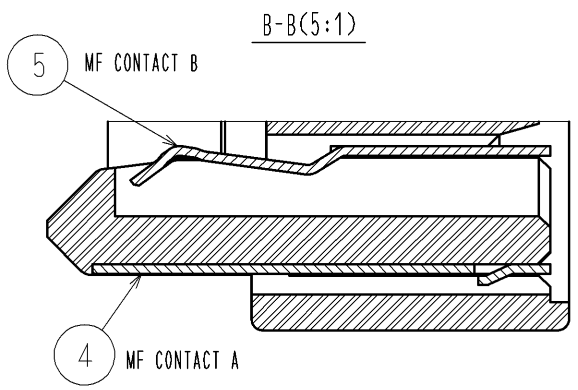
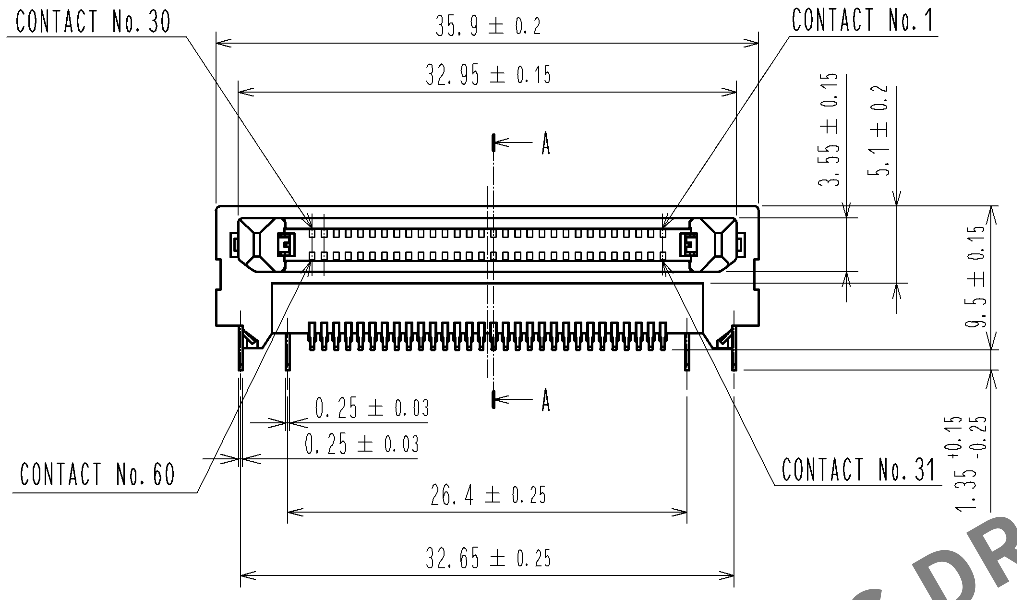
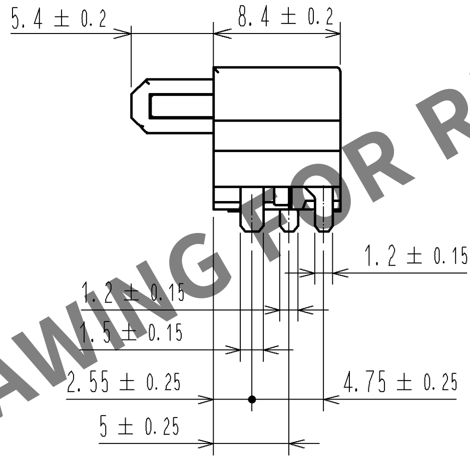
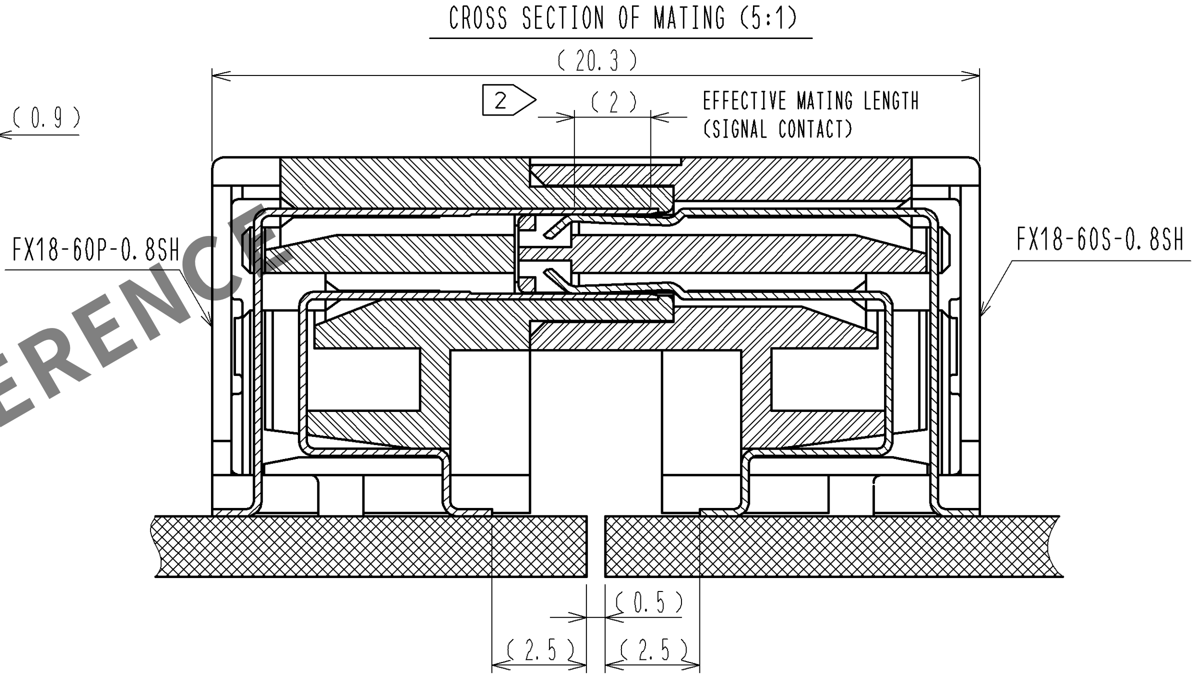


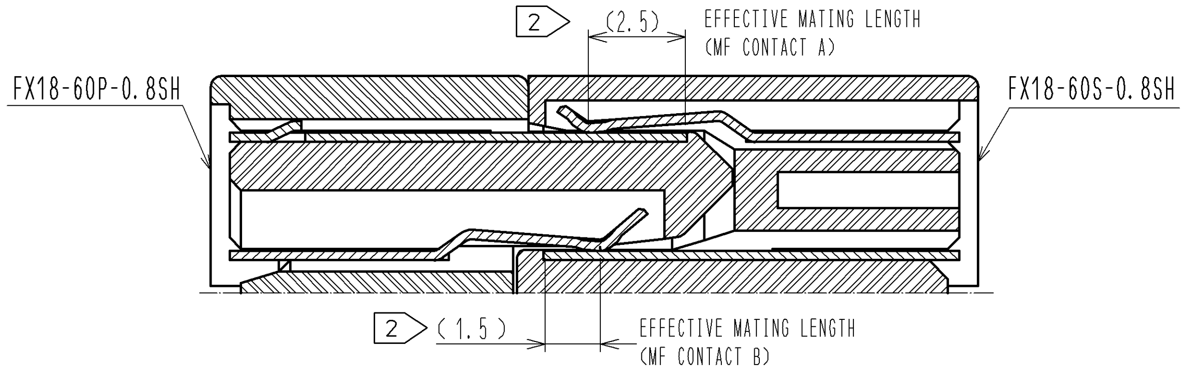


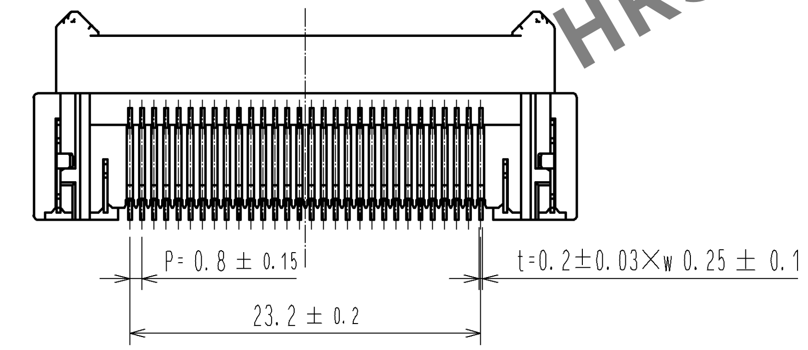












NOTE 1 LEAD CO—PLANARITY IS 0.1mm MAX.
2 CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A=>SIGNAL CONTACT=>MF CONTACT B)
WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.
3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)
4 IT SHOWS CONNECTOR'S CENTRE OF GRAVITY AND VACUUM PICKUP AREA.
5 PACKING FOR PRODUCT APPLIES EMBOSSED CARRIER TAPE PACKING.(300pcs/RL)
6 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN'T AFFECT QUALITY LEVEL.
7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.
△1 8 SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES.
BE SURE TO CONNECT TO THE SAME CIRCUIT.

NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
			7	POLYESTER	(EMBOSSED COVER TAPE)
3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1μm	6	POLYSTYRENE	(EMBOSSED CARRIER TAPE)
		LEAD AREA:GOLD 0.03μm	5	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1μm
		UNDER PLATING:NICKEL 1.3μm			LEAD AREA:TIN-PLATING 1μm
2	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1μm			UNDER PLATING:NICKEL 1.3μm
		LEAD AREA:GOLD 0.03μm	4	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1μm
		UNDER PLATING:NICKEL 1.3μm			LEAD AREA:TIN-PLATING 1μm
1	POLYAMIDE	BLACK UL94V-0			UNDER PLATING:NICKEL 1.3μm

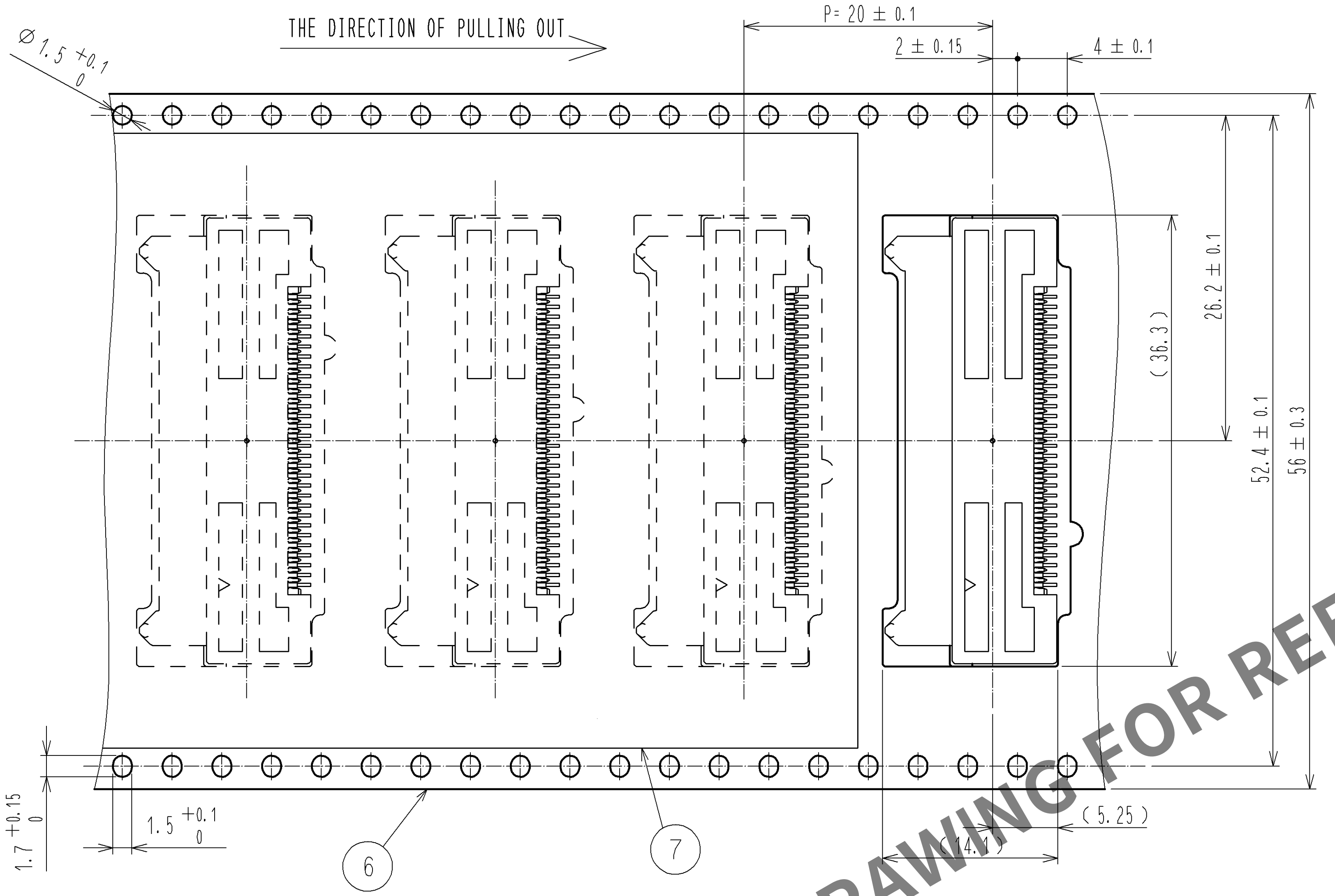
UNITS	SCALE		COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	2 : 1	△1	5	DIS-F-005578	TH. SANO	KI. HIROKAWA	11.07.21

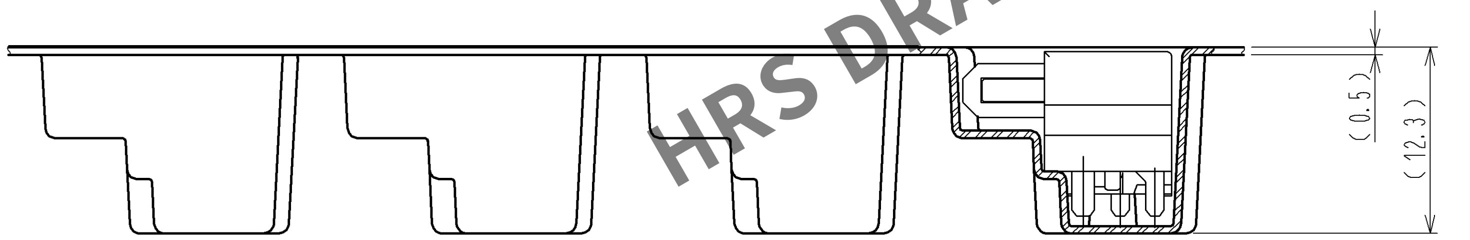
HIROSE
ELECTRIC
CO., LTD.

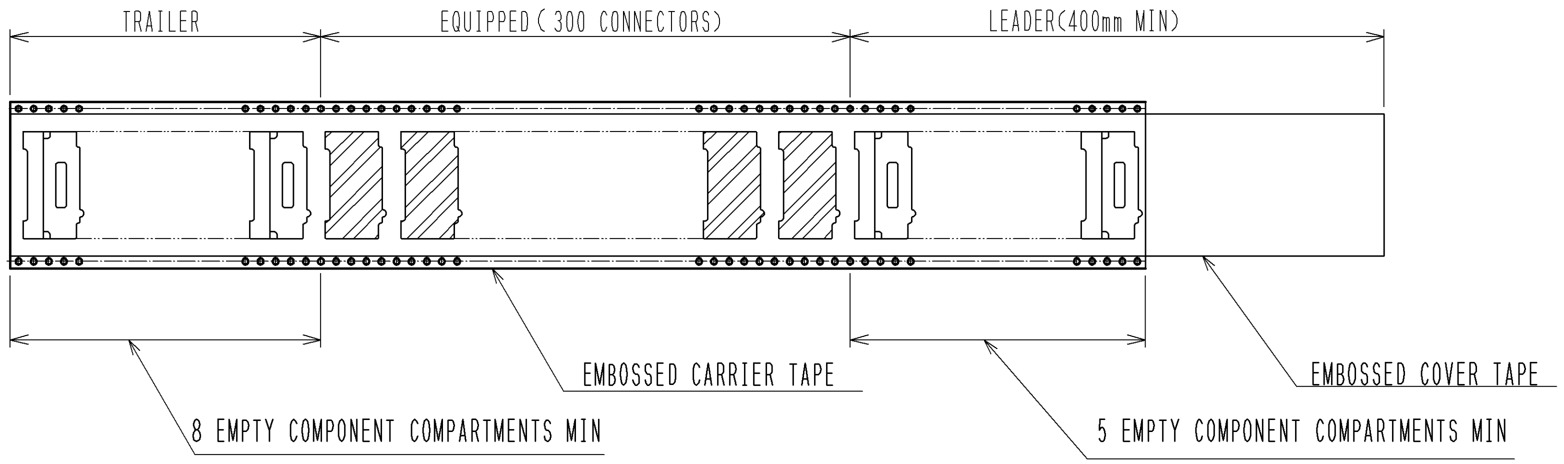
APPROVED	:HS. OKAWA	10.05.10
CHECKED	:KI. HIROKAWA	10.05.10
DESIGNED	:TH. SANO	10.05.10
DRAWN	:KI. HIROKAWA	10.03.04

DRAWING NO. EDC3-159075-02
PART NO. FX18-60P-0.8SH(11)
CODE NO. CL579-0003-8-11 △1 1/2

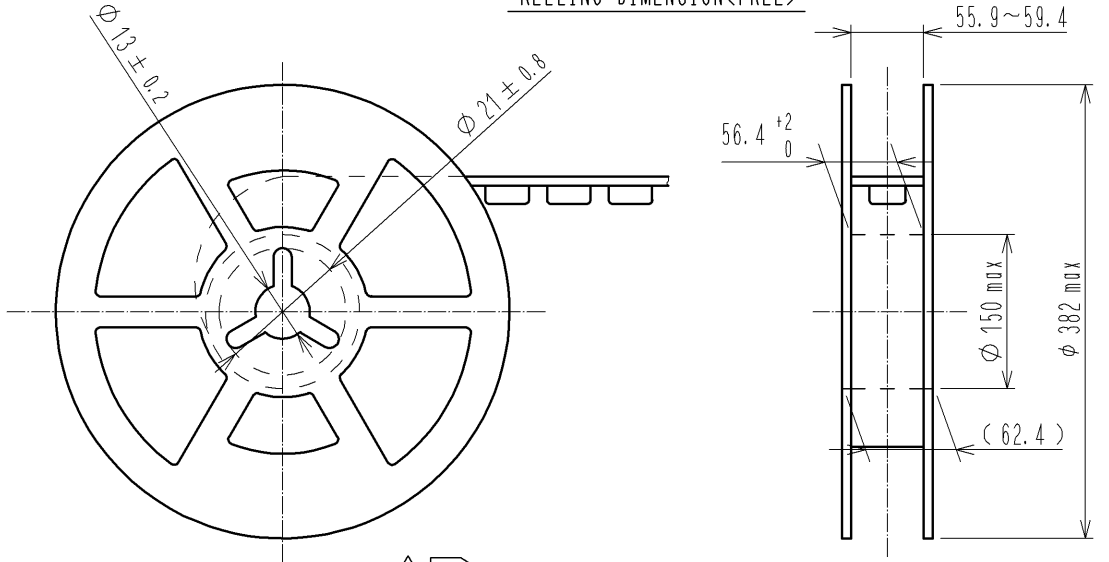
5 DRAWING FOR PACKING (2:1)



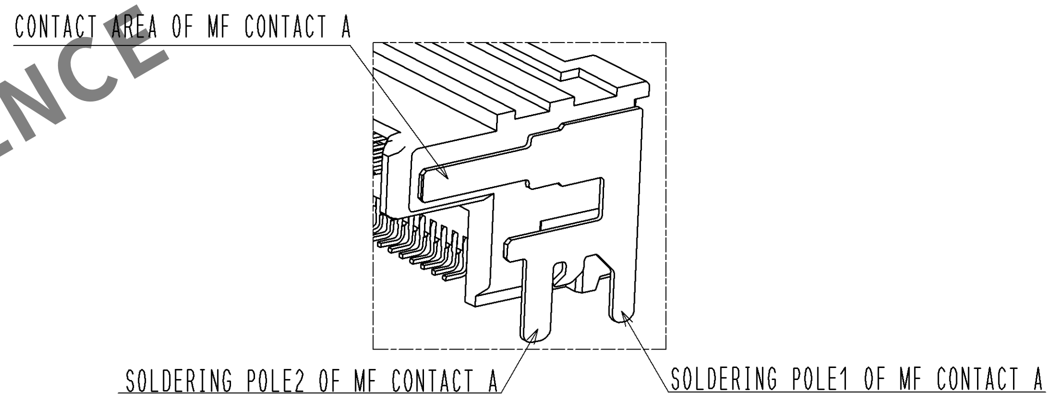




REELING DIMENSION(FREE)

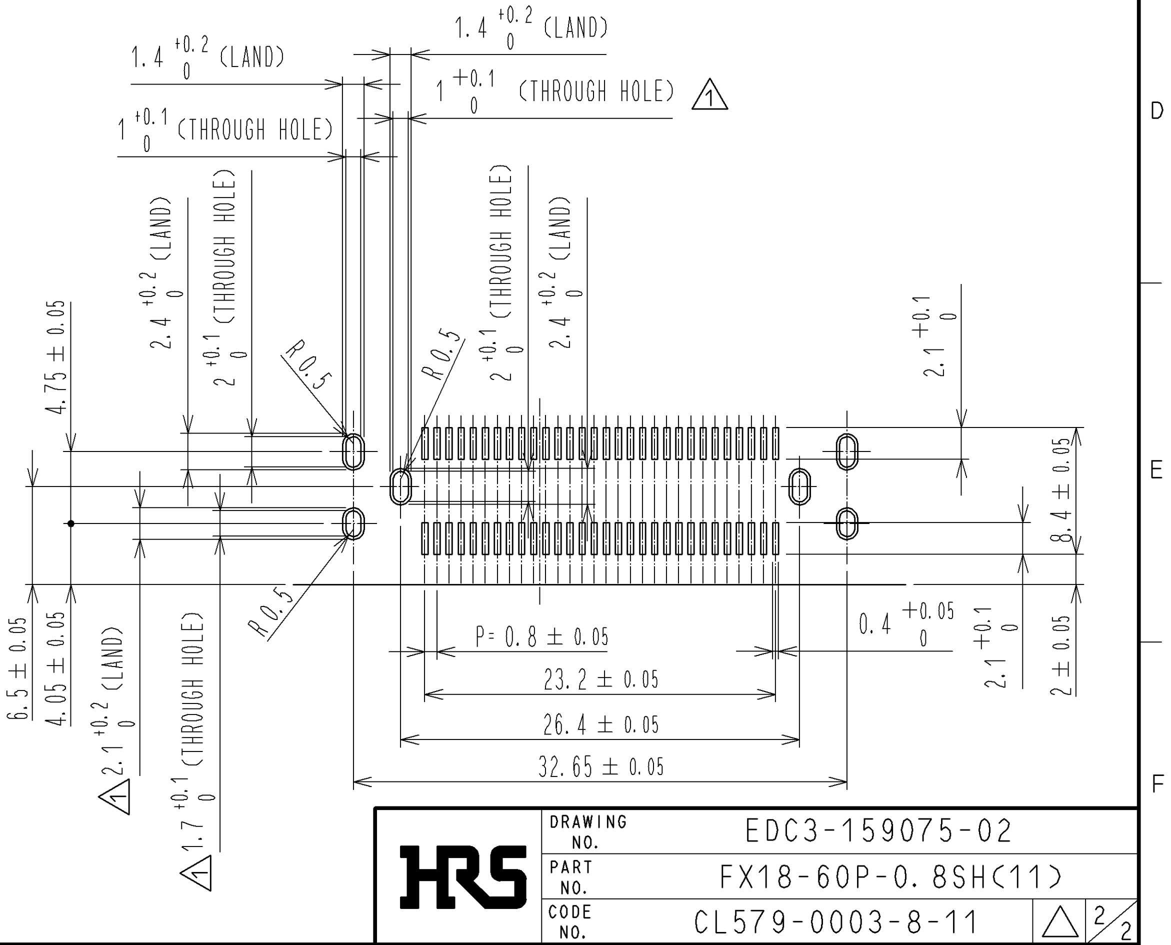


1 8 CONFIGURATION OF MF CONTACT A



RECOMMENDED LAND PATTERN DIMENSION OF PCB(2:1)

(PCB THICKNESS: t=1.6mm METAL MASK THICKNESS : t=0.12mm)



DRAWING NO.	EDC3-159075-02
PART NO.	FX18-60P-0.8SH(11)
CODE NO.	CL579-0003-8-11 △ 2/2